

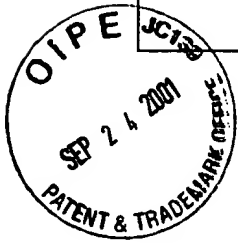
CERTIFICATE OF HAND DELIVERY

I hereby certify that this correspondence is being hand filed with the United States Patent and Trademark Office in Washington, D.C. on September 24, 2001.

Melissa Garton
Melissa Garton

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



In the application of:

Tomohiro HASHII

Serial No.: 09/594,502

Filing Date: June 16, 2000

For: SEMICONDUCTOR WAFER
GRINDING METHOD

Examiner: Robert A. Rose

Group Art Unit: 3723

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AMENDMENT UNDER 37 CFR 1.111

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

In response to the Office Action dated May 24, 2001, Applicants request a 1-Month Extension of Time, as noted in the attached Petition, extending the period for response from August 24, 2001 to September 24, 2001. Please amend this application as follows:

IN THE CLAIMS

Please cancel claims 1-4 without prejudice or disclaimer.

Please add the following new claims:

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Sub
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- 5. A method for grinding semiconductor wafers comprising:
grinding a surface of a semiconductor wafer with fixed abrasive grains;